

SOT1177-1

plastic extremely thin small outline package; no leads; 10 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON10
Package type industry code	XSON10
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	8-11-2010

Table 1. Package summary

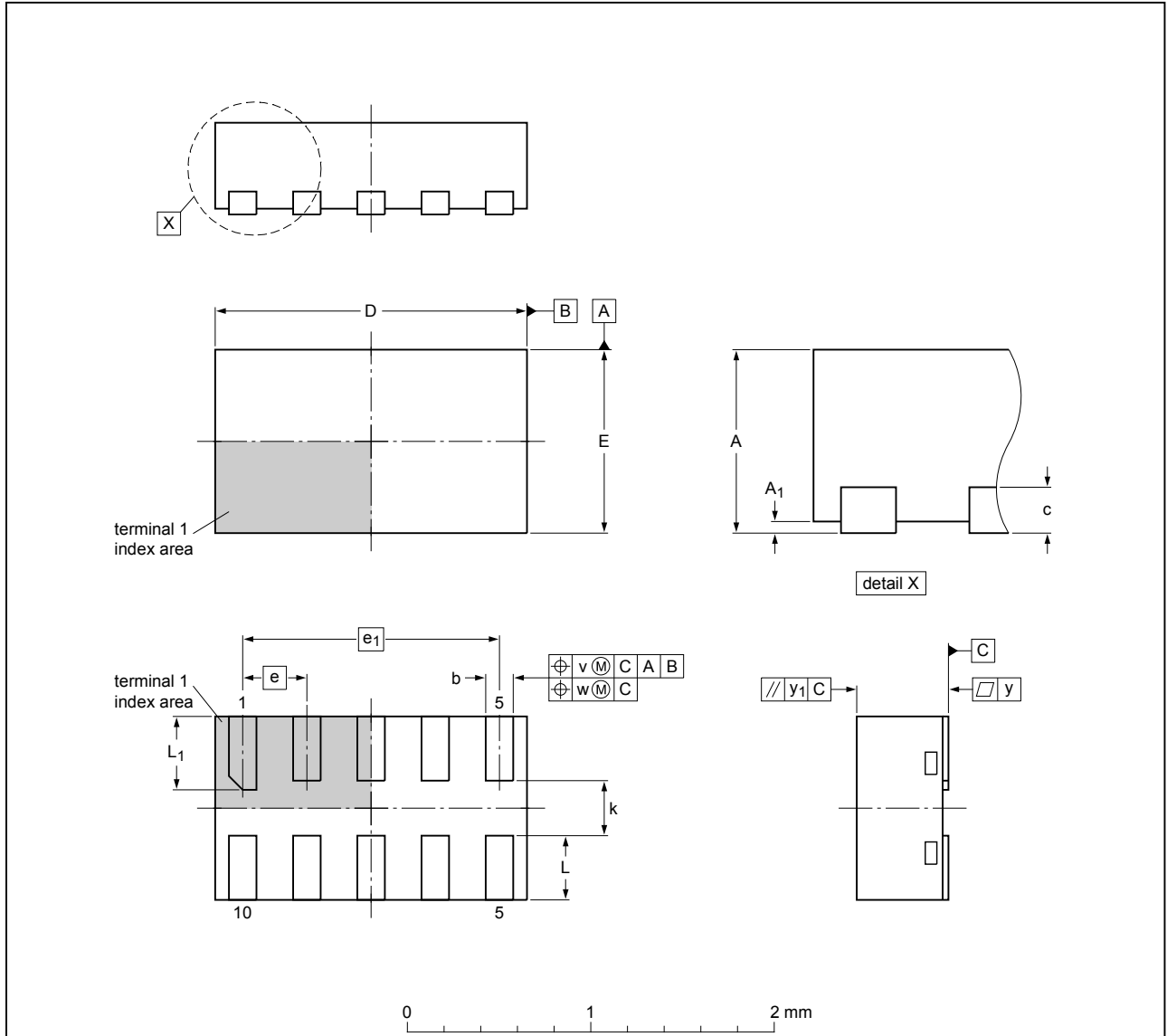
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.6	-	1.7	1.8	mm
E	package width	0.9	-	1	1.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.35	-	mm
n ₂	actual quantity of termination	-	-	10	-	



2. Package outline

XSON10: plastic extremely thin small outline package; no leads; 10 terminals; body 1.0 x 1.7 x 0.5 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	b	c	D	E	e	e ₁	k	L	L ₁	v	w	y	y ₁
max	0.5	0.05	0.20		1.8	1.1				0.40	0.45				
mm nom			0.15	0.127	1.7	1.0	0.35	1.4		0.35	0.40	0.1	0.05	0.05	0.05
min		0.00	0.10		1.6	0.9			0.2	0.30	0.35				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline XSON10 (SOT1177-1)

3. Legal information

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